

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yong L. Xu</td> <td>02/14/2012</td> </tr> <tr> <td>Viren Khandekar</td> <td>02/14/2012</td> </tr> <tr> <td>Yi-Sheng A. Sun</td> <td>02/14/2012</td> </tr> <tr> <td>Arkadii Samoilov</td> <td>02/14/2012</td> </tr> </tbody> </table>		Name	Execution Date	Yong L. Xu	02/14/2012	Viren Khandekar	02/14/2012	Yi-Sheng A. Sun	02/14/2012	Arkadii Samoilov	02/14/2012
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RECEIVING PARTY DATA											
Name:	Maxim Integrated Products, Inc.										
Street Address:	120 San Gabriel Drive										
City:	Sunnyvale										
State/Country:	CALIFORNIA										
Postal Code:	94086										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13396804</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13396804						
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Application Number:	13396804										
CORRESPONDENCE DATA											
Fax Number:	(402)504-1636										
Phone:	402.502.1020										
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name:	Advent IP/Maxim										
Address Line 1:	2425 South 144th Street, Suite 202										
Address Line 4:	Omaha, NEBRASKA 68144										
ATTORNEY DOCKET NUMBER:	MAXM-1080										
NAME OF SUBMITTER:	Kevin E. West										
Total Attachments: 6											

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ASSIGNMENT

WHEREAS, we, Yong L. Xu, residing at 4000 Breanna Way, Plano, TX 75024, Viren Khandekar, residing at 2700 Wisdom Creek Drive, Flower Mound, TX 75022, Yi-Sheng A. Sun, residing at 2914 Creek Point Drive, San Jose, CA 95133, and Arkadii Samoilov, residing at 14472 Oak Place, Saratoga, CA 95070, have made certain new and useful inventions and improvements to an application for Letters Patent of the United States which is entitled "WAFER-LEVEL PACKAGE DEVICE HAVING SOLDER BUMP ASSEMBLIES THAT INCLUDE AN INNER PILLAR STRUCTURE" will be filed. The undersigned hereby authorize and request Assignee's legal representatives of ADVENT IP, P.C., L.L.O., who are associated with Customer No. 99900, to insert herein in parenthesis (U.S. Application Serial No. 13/396,804, filed on February 15, 2012) the application's serial number and filing date when known.

AND WHEREAS, Maxim Integrated Products, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 120 San Gabriel Drive, Sunnyvale, CA 94086 (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW THEREFORE, to all whom it may concern, be it known that for and in consideration of the sum of One Dollar and other good and valuable considerations, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the

Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

Dated:

2-14-2012



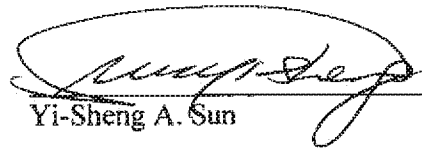
Yong L. Xu

Dated: 2/14/2012



Viren Khandekar

Dated: 07/14/2012


Yi-Sheng A. Sun

Dated: _____

02/14/2012

Arkadii Samoilov

Arkadii Samoilov